

SPECIFICATION FOR APPROVAL

CUSTOMER : _____

PRODUCT TYPE : SMD TUNING FORK 1.2X1.0

NOMINAL FREQ. : 32.768 KHz

TXC P/N : 9H03270079

REVISION : A1

CUSTOMER P/N : _____

PM / SALES : _____

DATE : _____

CUSTOMER CONFIRMATION : _____
(Singnature)

_____ (Date)

RoHS Compliant
Halogen Free

PRODUCT SPECIFICATION SHEET

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NOMINAL FREQ. : 32.768 KHz

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PE/RD	QA	MFG
<i>James Chung</i>	<i>Shipo Lin</i>	<i>Shu-Chen ko</i>
James Chung	Shipo Lin	Shu-Chen Ko
2019/7/10	2019/7/10	2019/7/10

RoHS Compliant
Halogen Free

Spec Sheet Contents

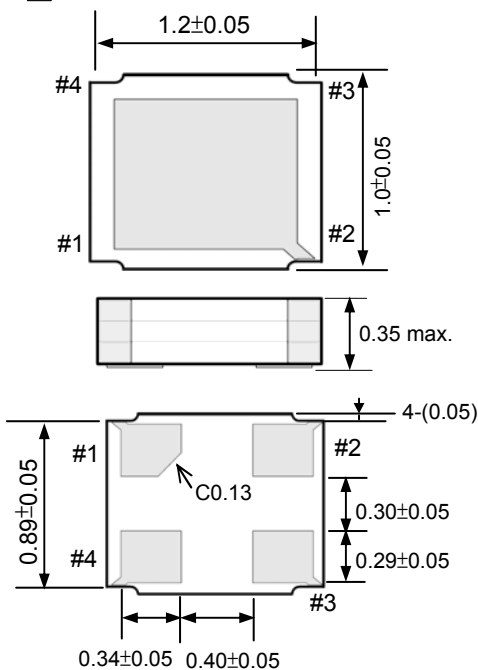
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ELECTRICAL SPECIFICATIONS

	Parameters	Sym.	Electrical Spec.				Notes
			Min.	Typical	Max.	Unit	
1	Nominal Frequency	F0	32.768			KHz	-
2	Frequency Tolerance	$\Delta f/f_0$	-20		+20	ppm	at 25 °C $\pm 3^\circ\text{C}$
3	Load Capacitance	CL	7.0			pF	-
4	Driver Level	DL	-	0.1	0.5	μW	-
5	Equivalent Series Resistance	ESR	-	-	90	K Ω	at 25 °C $\pm 3^\circ\text{C}$
6	Turnover Temperature	Tp	20	25	30	°C	at 25 °C $\pm 5^\circ\text{C}$
7	Parabolic Curvature Constant	K	-	-0.034	-0.039	ppm/°C ²	-
8	Operating Temperature	-	-40	~	85	°C	-
9	Storage Temperature	-	-55	~	125	°C	-
10	Insulation Resistance	IR	500	-	-	M Ω	at DC 100V $\pm 15\text{V}$
11	Shunt Capacitance	C0	-	1.5	-	pF	-
12	Motional Capacitance	C1	-	7.0	-	fF	-
13	Aging	$\Delta f/f$	-3		+3	ppm	1st Year

FACTORY LOCATION : CHINA

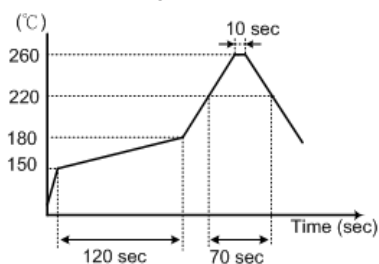
DIMENSIONS (UNIT:mm)



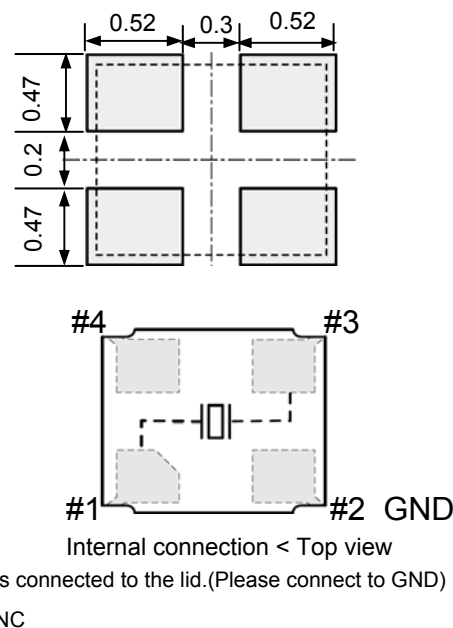
REFLOW PROFILE

Total time : 200 sec. Max.

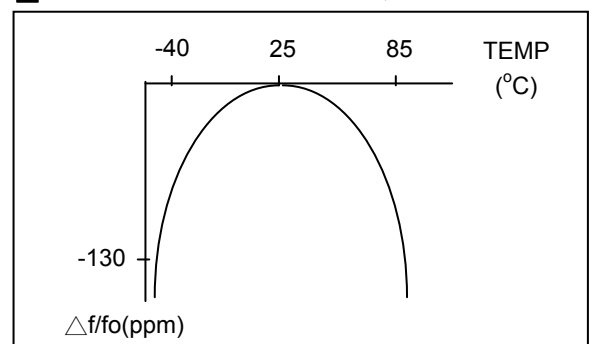
Solder melting point : 220 °C



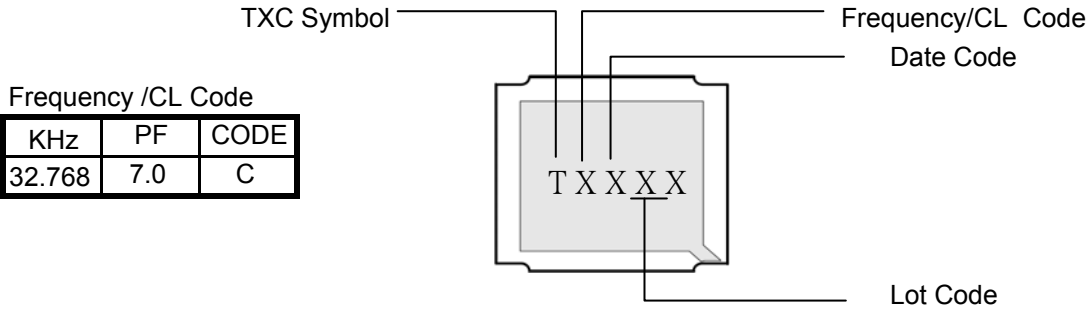
RECOMMENDED SOLDER PAD (UNIT:mm)



TEMPERATURE V.S FREQUENCY CURVE



MARKING



Frequency /CL Code

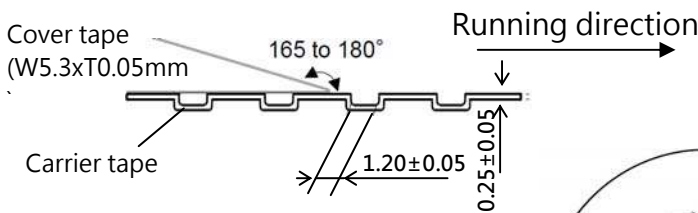
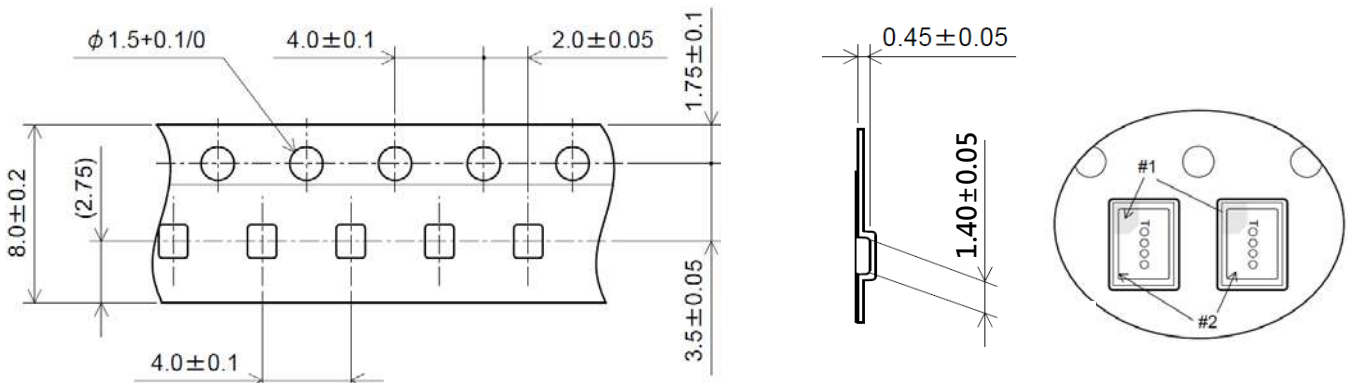
KHz	PF	CODE
32.768	7.0	C

Date Code

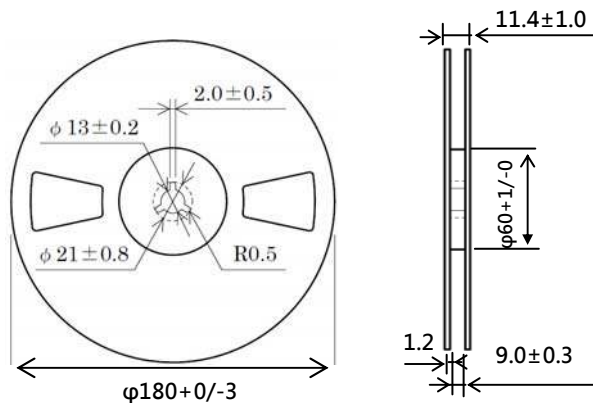
YEAR					MONTH											
					JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2013	2017	2021	2025	2029	A	B	C	D	E	F	G	H	J	K	L	M
2014	2018	2022	2026	2030	N	P	Q	R	S	T	U	V	W	X	Y	Z
2015	2019	2023	2027	2031	a	b	c	d	e	f	g	h	j	k	l	m
2016	2020	2024	2028	2032	n	p	q	r	s	t	u	v	w	x	y	z

This date code will be cycled every four years

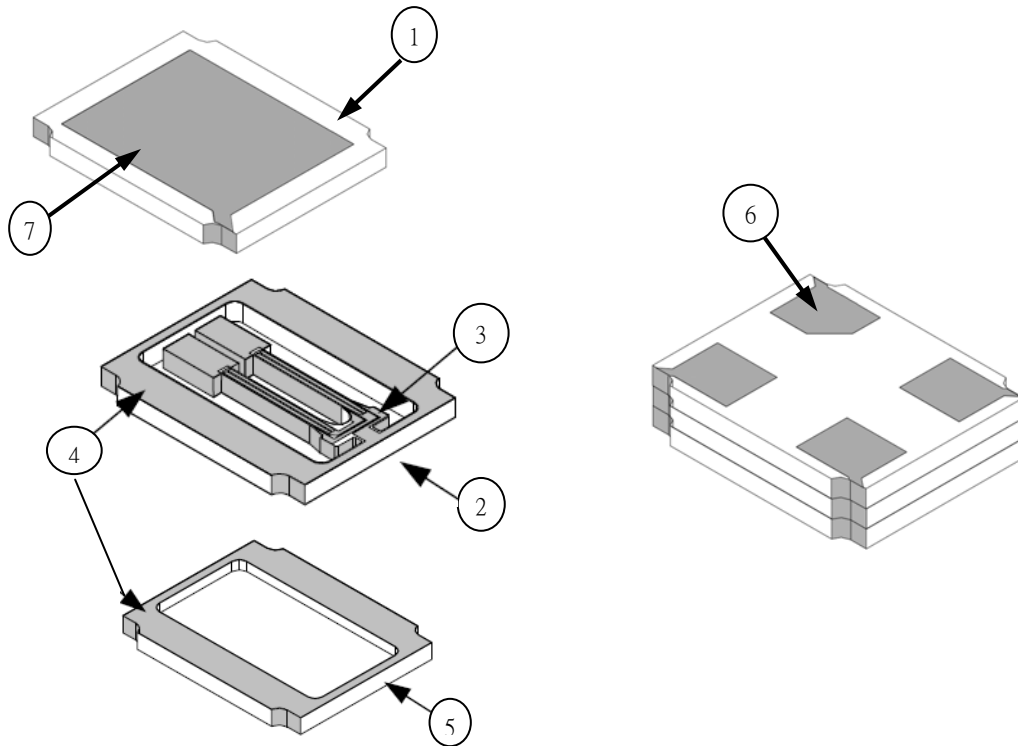
PACKING (UNIT:mm)



Material : Conductive Polystyrene
Quantity : 5000 pieces max./Reel



- REMARK :
- 230 mm (9.05) minimum leader which consist of carrier and/or tape followed by a minimum of 160 mm (6.3) of empty carrier tape sealed with cover tape.
 - 160 mm (6.3) minimum trailer of empty carrier tape sealed with cover tape.

■ STRUCTURE ILLUSTRATION


NO	COMPONENTS		MATERIALS	QTY	FINISH/SPECIFICATIONS
1	Cap	Quartz	SiO ₂	1	-
2	Chip	Quartz	SiO ₂	1	-
3		Electrode	Noble Metal	2	Cr+Au
4	Base	Metal for sealing	Chrome(Cr)+Gold(Au)	1	
5		Quartz	SiO ₂	1	
6		PAD	Substratum(Chromium(Cr)/Copper(Cu))	2	Ni plating + Au plating
7	Marking display	PAD	Substratum(Chromium(Cr)/Copper(Cu))	1	Ni plating + Au plating

■ UNIT WEIGHT:

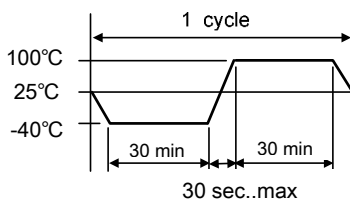
0.0008±0.00015 g/pcs

RELIABILITY SPECIFICATIONS

1. Mechanical Endurance

No.	Test Item	Test Methods	REF. DOC
1.1	Drop Test	100 cm height, fall freely onto concrete floor 3 times.	MIL-STD-202
1.2	Mechanical Shock	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times. 1m sec. duration time	MIL-STD-202
1.3	Vibration	Frequency range 10 ~ 55 Hz Amplitude 1.5 mm Sweep time 1 minute Perpendicular axes each test time 2 hours (Total test time 6 hours)	MIL-STD-883
1.4	Solderability	Temperature 255 °C ± 5°C Immersing depth 0.5 mm minimum Immersion time 3.5 ± 0.5 seconds Flux Rosin resin methyl alcohol solvent (1 : 4)	MIL-STD-883

2. Environmental Endurance

No.	Test Item	Test Methods	REF. DOC
2.1	Resistance To Soldering Heat	Pre-heat temperature 160 °C Pre-heat time 90 ± 10 sec. Test temperature 260 ± 5 °C Test time 5 ± 1 sec.	MIL-STD-202
2.2	High Temp. Storage	+ 100 °C ± 3 °C for 100 ± 12 hours	MIL-STD-883
2.3	Low Temp. Storage	- 40 °C ± 3 °C for 1000 ± 12 hours	MIL-STD-883
2.4	Thermal Shock	Total 100 cycles of the following temperature cycle 	MIL-STD-883
2.5	High Temp & Humidity	40 °C ± 3 °C, RH 95% , 1000Hrs	EIA-JESD22

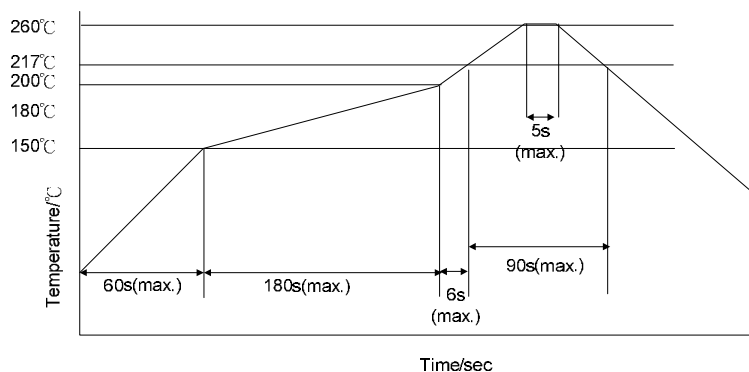


Figure 1. Soldering Temperature Reflow Profile

■ **Important Notice**

This crystal component is not designed for any life-threatening usage or applications.

Do not use this product for any life-threatening applications.

Examples of life-threatening applications include main functions of automotive or medical devices and all kinds of military applications.

■ **Standard atmospheric conditions**

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

- Ambient temperature : 25±5°C
- Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

- Ambient temperature : 25±3°C
- Relative humidity : 40%~70%

■ **Measurement condition**

Electrical characteristics measured by S&A250B or equivalent.

NOTE:

1. TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
2. Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
3. Any changes to these specifications must be agreed upon by both parties and new revision of the "Product Specification Sheet" will be issued.
4. Any issuance of purchase order prior to consigning back the approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.
5. The green product standard set by TXC is based upon the international standards. Related information is publicly described on the TXC's website, and updated regularly. The document is compliant with the latest green product quality system directives at the time.
6. Revision "Sx" is for engineering samples only. PE/RD's approval required.
7. Revision "Ax" is production ready. PE, QA and MFG's approval required.
8. Inform TXC in advance if you use ultrasonic welding in assembling process .